Abstracts

Millimeter-Wave Performance of Chip Interconnections Using Wire Bonding and Flip Chip

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The performances of two different interconnection techniques for coplanar MMICs, wire bonding and flip chip, are investigated at Millimeter-Wave frequencies. By developing an accurate model for the interconnections, which is validated with experimental data up to 120 GHz, the limitations with respect to frequency and interconnection distance of either technique are pointed out, yielding useful data for the design of hybrid MMW-subsystems.

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